

IGBT - Ultra Field Stop 1200 V, 40 A, $V_{CE(Sat)} = 1.55V$, T0247 4L FGH4L40T120LQD

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost-effective Ultra Field Stop Trench construction, and provides superior performance in demanding switching applications, offering both low on-state voltage and minimal switching loss. The IGBT is well suited for motor driver applications. Incorporated into the device is a soft and fast co-packaged free-wheeling diode with a low forward voltage.

Features

- Extremely Efficient Trench with Field Stop Technology
- Maximum Junction Temperature: $T_J = 175^{\circ}C$
- Fast and Soft Reverse Recovery Diode
- Optimized for Low V_{CE(Sat)}

Typical Applications

- Solar Inverter and UPS
- Industrial Switching
- Welding

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CE}	1200	V
Gate-Emitter Voltage Transient Gate-Emitter Voltage	V_{GE}	±20 ±30	V
Collector Current @ $T_C = 25^{\circ}C$ (Note 1) @ $T_C = 100^{\circ}C$	I _C	80 40	Α
Pulsed Collector Current (Note 2)	I _{LM}	160	Α
Pulsed Collector Current (Note 3)	I _{CM}	160	Α
Diode Forward Current @ $T_C = 25^{\circ}C$ (Note 1) @ $T_C = 100^{\circ}C$	l _F	80 40	Α
Maximum Power Dissipation @ T _C = 25°C @ T _C = 100°C	P _D	306 153	W
Operating Junction and Storage Temperature Range	T _J , T _{STG}	–55 to +175	°C
Maximum Lead Temp. for Soldering Purposes (1/8" from case for 5 s)	T_L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Value limit by bond wire
- 2. V_{CC} = 600 V, V_{GE} = 15 V, I_{C} = 160 A, R_{G} = 15 Ω , Inductive Load, 100% Tested
- 3. Repetitive rating: Pulse width limited by max. junction temperature



TO-247-4LD CASE 340CJ

MARKING DIAGRAM



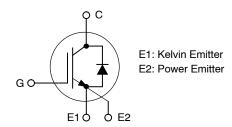
FGH40T120LQD = Specific Device Code

\$Y = onsemi Logo

&Z = Assembly Plant Code &3 = 3-Digit Date Code

&K = 2-Digit Lot Traceability Code

PIN CONNECTIONS



ORDERING INFORMATION

Device	Package	Shipping
FGH4L40T120LQD	TO-247	30 Units / Rail

THERMAL CHARACTERISTICS

Rating	Symbol	Min	Тур	Max	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ heta JC}$	-	0.38	0.49	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ heta JC}$	-	0.64	0.84	°C/W
Thermal resistance junction-to-ambient	$R_{\theta JA}$	-	-	40	°C/W

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTIC	•	•				•
Collector-Emitter Breakdown Voltage	V _{GE} = 0 V, I _C = 1 mA	BV _{CES}	1200	-	-	V
Temperature Coefficient of Breakdown Voltage	V _{GE} = 0 V, I _C = 1 mA	$\Delta BV_{CES}/\Delta T_{J}$	-	1.3	_	V/°C
Collector-Emitter Cut-Off Current	V _{GE} = 0 V, V _{CE} = 1200 V	I _{CES}	-	_ 500	40 -	μΑ
Gate Leakage Current	V _{GE} = 20 V, V _{CE} = 0 V	I _{GES}	-	-	200	nA
ON CHARACTERISTIC	•	-				
Gate-Emitter Threshold Voltage	$V_{GE} = V_{CE}$, $I_C = 40 \text{ mA}$	V _{GE(th)}	5.5	6.5	7.5	V
Collector-Emitter Saturation Voltage	V _{GE} = 15 V, I _C = 40 A, T _J = 25°C	V _{CE(sat)}	-	1.55	1.80	V
	V _{GE} = 15 V, I _C = 40 A, T _J = 175°C		-	2	-	1
DYNAMIC CHARACTERISTIC	•					
Input Capacitance		C _{ies}	-	5079	-	pF
Output Capacitance	V _{CE} = 30 V, V _{GE} = 0 V, f = 1 MHz	C _{oes}	-	113	-	
Reverse Transfer Capacitance	7	C _{res}	-	62	-	1
Gate Charge Total		Q_g	-	227	-	nC
Gate-to-Emitter Charge	V _{CC} = 600 V, I _C = 40 A, V _{GE} = 15 V	Q _{ge}	-	40	-	1
Gate-to-Collector Charge	7	Q _{gc}	_	108	-	1
SWITCHING CHARACTERISTIC, INDUC	TIVE LOAD					
Turn-on Delay Time		t _{d(on)}	-	38	-	ns
Rise Time	7	t _r	-	13	-	
Turn-off Delay Time	$T_J = 25^{\circ}C$ $V_{CC} = 600 \text{ V, } I_C = 20 \text{ A}$	t _{d(off)}	-	227	-	
Fall Time	$R_q = 10 \Omega$	t _f	-	51	-	
Turn-on Switching Loss	V _{GE} = 15 V Inductive Load	E _{on}	-	0.63	-	mJ
Turn-off Switching Loss	7	E _{off}	-	0.77	-	
Total Switching Loss	7	E _{ts}	-	1.40	-	1
Turn-on Delay Time		t _{d(on)}	-	42	-	ns
Rise Time	7	t _r	-	19	-	1
Turn-off Delay Time	T _J = 25°C V _{CC} = 600 V, I _C = 40 A	t _{d(off)}	-	218	-	1
Fall Time	$R_{q} = 10 \Omega$	t _f	-	80	-	1
Turn-on Switching Loss	V _{GE} = 15 V Inductive Load	E _{on}	-	1.04	-	mJ
Turn-off Switching Loss	1	E _{off}	-	1.35	-	1
Total Switching Loss	1	E _{ts}	-	2.39	-	1

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
SWITCHING CHARACTERISTIC, INDU	ICTIVE LOAD	•	-	•	-	-
Turn-on Delay Time		t _{d(on)}	-	32	_	ns
Rise Time		t _r	_	12	-	1
Turn-off Delay Time	$T_J = 175^{\circ}C$ $V_{CC} = 600 \text{ V, } I_C = 20 \text{ A}$	t _{d(off)}	_	264	_	1
Fall Time	$R_g = 10 \Omega$	t _f	_	156	_	1
Turn-on Switching Loss	V _{GE} = 15 V Inductive Load	E _{on}	_	1.05	-	mJ
Turn-off Switching Loss		E _{off}	_	1.62	-	
Total Switching Loss		E _{ts}	_	2.67	-	
Turn-on Delay Time		t _{d(on)}	_	36	-	ns
Rise Time		t _r	_	20	-	
Turn-off Delay Time	$T_J = 175$ °C $V_{CC} = 600 \text{ V, I}_C = 40 \text{ A}$	t _{d(off)}	-	236	-	
Fall Time	$R_q = 10 \Omega$	t _f	-	204	-	1
Turn-on Switching Loss	V _{GE} = 15 V Inductive Load	E _{on}	_	1.62	-	mJ
Turn-off Switching Loss		E _{off}	-	2.51	-	
Total Switching Loss		E _{ts}	-	4.13	-	
DIODE CHARACTERISTIC						
Forward Voltage	V _{GE} = 0 V, I _F = 40 A, T _J = 25°C	V _F	-	3.31	3.80	V
	V _{GE} = 0 V, I _F = 40 A, T _J = 175°C		-	2.97	-	1
Reverse Recovery Energy	T _J = 25°C	E _{REC}	-	126	-	μJ
Diode Reverse Recovery Time	$I_F = 40 \text{ A}, V_R = 600 \text{ V}$	T _{rr}	-	59	-	ns
Diode Reverse Recovery Charge	di _F /dt = 1000 A/μs	Q _{rr}	_	804	-	nC
Reverse Recovery Energy	T _{.l} = 175°C	E _{REC}	_	540	-	μJ
Diode Reverse Recovery Time	$I_F = 20 \text{ A}, V_R = 600 \text{ V}$	T _{rr}	_	115	-	ns
Diode Reverse Recovery Charge	di _F /dt = 1000 A/μs	Q _{rr}	-	2090	-	nC
Reverse Recovery Energy	T _J = 175°C	E _{REC}	-	667	-	μJ
Diode Reverse Recovery Time	$I_F = 40 \text{ A}, V_R = 600 \text{ V}$	T _{rr}	-	127	-	ns
Diode Reverse Recovery Charge	di _F /dt = 1000 A/μs	Q _{rr}	_	2613	-	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

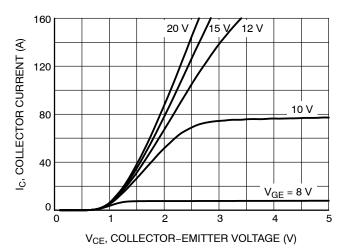


Figure 1. Typical Output Characteristics $(T_J = 25^{\circ}C)$

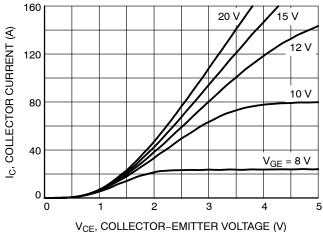


Figure 2. Typical Output Characteristics

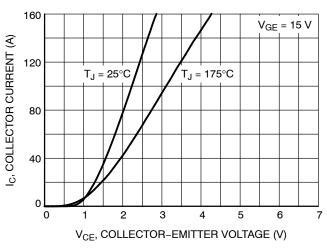


Figure 3. Typical Saturation Voltage Characteristics

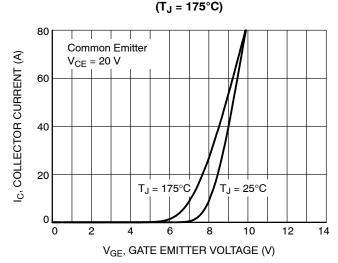


Figure 4. Typical Transfer Characteristics

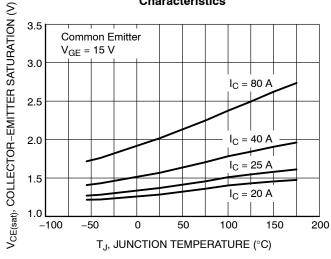
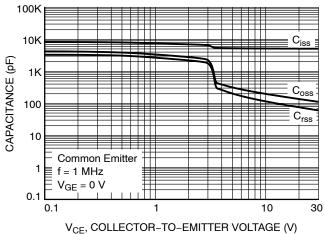


Figure 5. Saturation Voltage vs. Junction **Temperature**



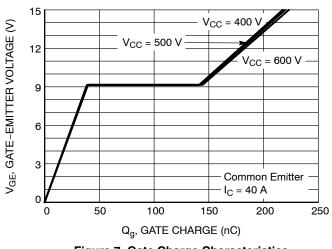


Figure 7. Gate Charge Characteristics

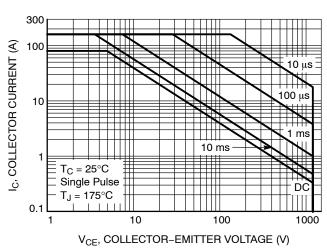


Figure 8. SOA Characteristics (FBSOA)

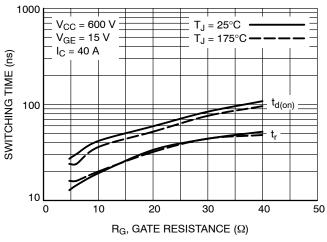


Figure 9. Turn-on Characteristics vs. Gate Resistance

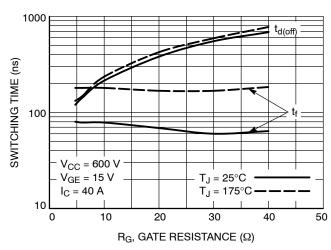


Figure 10. Turn-off Characteristics vs. Gate Resistance

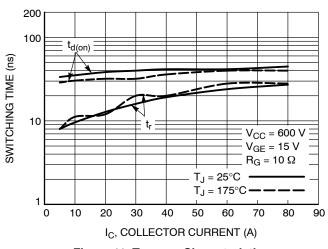


Figure 11. Turn-on Characteristics vs.
Collector Current

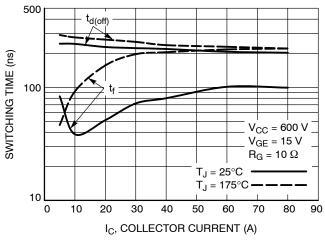


Figure 12. Turn-off Characteristics vs.
Collector Current

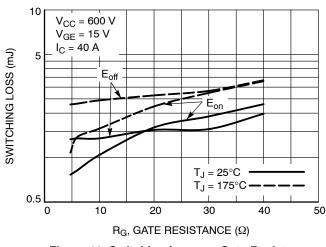


Figure 13. Switching Loss vs. Gate Resistance

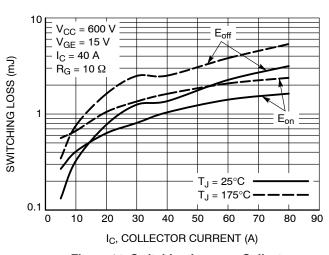


Figure 14. Switching Loss vs. Collector Current

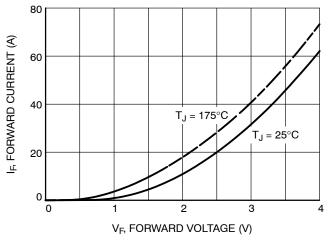


Figure 15. (Diode) Forward Characteristics

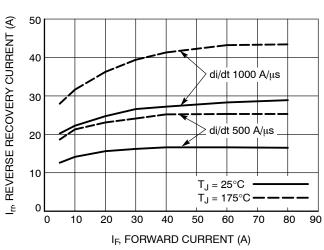


Figure 16. (Diode) Reverse Recover Current vs. Forward Current

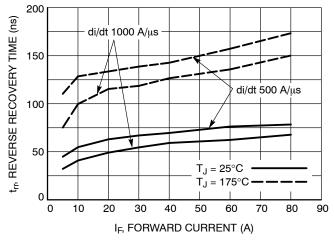


Figure 17. (Diode) Reverse Recovery Time

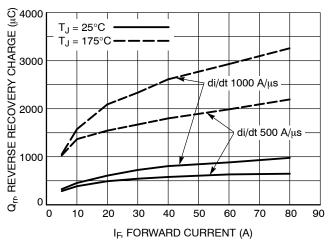


Figure 18. (Diode) Stored Charge

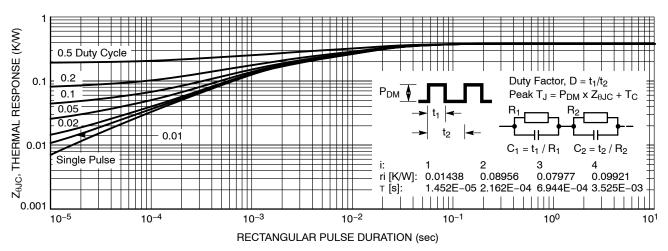


Figure 19. Transient Thermal Impedance of IGBT

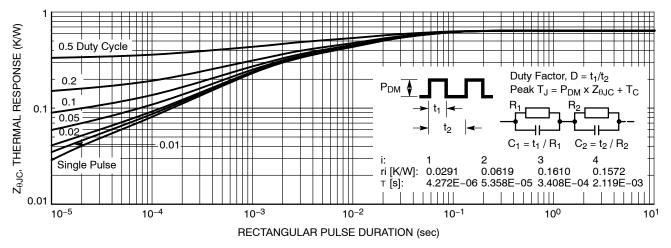


Figure 20. Transient Thermal Impedance of Diode

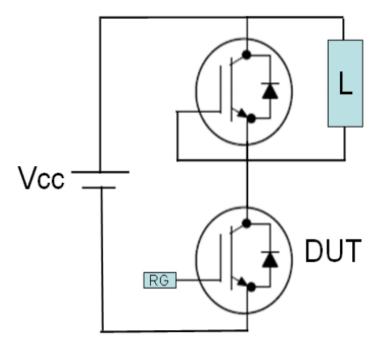


Figure 21. Test Circuits for Switching Characteristics

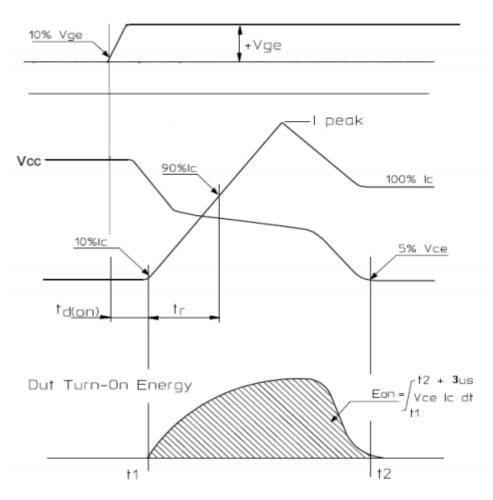


Figure 22. Definition of Turn-On Waveforms

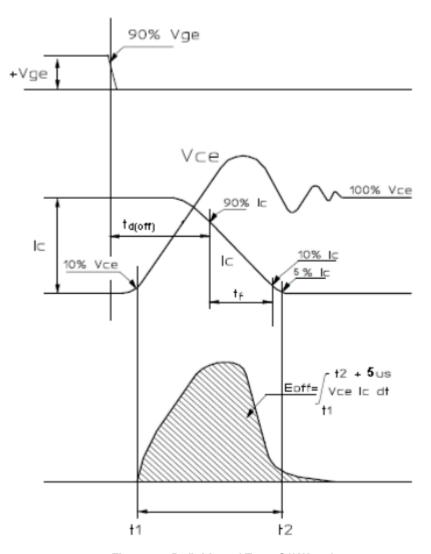
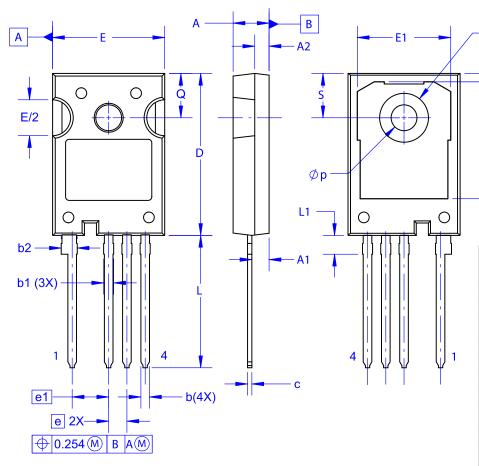


Figure 23. Definition of Turn-Off Waveforms

PACKAGE DIMENSIONS

TO-247-4LD CASE 340CJ ISSUE A



NOTES:

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
 B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
 FLASH, AND TIE BAR EXTRUSIONS.
 C. ALL DIMENSIONS ARE IN MILLIMETERS.
 D. DRAWING CONFORMS TO ASME Y14.5-2009.

DIM	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.80	5.00	5.20	
A1	2.10	2.40	2.70	
A2	1.80	2.00	2.20	
b	1.07	1.20	1.33	
b1	1.20	1.40	1.60	
b2	2.02	2.22	2.42	
С	0.50	0.60	0.70	
D	22.34	22.54	22.74	
D1	16.00	16.25	16.50	
D2	0.97	1.17	1.37	
е	2.54 BSC			
e1	5.08 BSC			
E	15.40	15.60	15.80	
E1	12.80	13.00	13.20	
E/2	4.80	5.00	5.20	
L	18.22	18.42	18.62	
L1	2.42	2.62	2.82	
р	3.40	3.60	3.80	
p1	6.60	6.80	7.00	
Q	5.97	6.17	6.37	
S	5.97	6.17	6.37	

Ø**p1**

D1

D2

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